APPLICATION DATA SHEET

Electronic Version v14 Stylesheet Version v14.0

Title of Invention

TILE-BASED ROUTING METHOD OF A MULTI-LAYER CIRCUIT BOARD AND RELATED STRUCTURE

Application Type:

regular, utility

Attorney Docket Number: SISP0002USA

Correspondence address:

Customer Number:

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Inventors Information:

Inventor 1:

Applicant Authority Type:

Inventor

Citizenship:

TW

Given Name:

Chung-Yi

Family Name:

Fang

City of Residence:

Hsin-Chu City

Country of Residence:

TW

Address-1 of Mailing Address:

7F-4, No. 68, Ta-Hsueh Rd.,

Address-2 of Mailing Address:

City of Mailing Address:

Hsin-Chu City

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address:

TW

Phone:

Fax:

E-mail:

Inventor 2:

Applicant Authority Type:

Inventor

Citizenship:

TW

Given Name:

Tze-Hsiang

Family Name:	Chao
City of Residence:	Hsin-Chu City
Country of Residence:	TW
Address-1 of Mailing Address:	5F-3, No. 9, Alley 19, Lane 550, Nan-Ta Rd.,
Address-2 of Mailing Address:	
City of Mailing Address:	Hsin-Chu City
State of Mailing Address:	
Postal Code of Mailing Address	:
Country of Mailing Address:	TW
Phone:	
Fax:	
E-mail:	
Inventor 3:	
Applicant Authority Type:	Inventor
Citizenship:	TW
Given Name:	Yi-Show
Family Name:	Su
City of Residence:	Tainan Hsien
Country of Residence:	TW
Address-1 of Mailing Address:	No. 220, Sec. 2, Hsin-Ching Rd., Hsin-Ying City,
Address-2 of Mailing Address:	
City of Mailing Address:	Tainan Hsien
State of Mailing Address:	
Postal Code of Mailing Address	:
Country of Mailing Address:	TW
Phone:	
Fax:	
E-mail:	
Attorney Information:	
practitioner(s) at Customer Number:	
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027765

as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.